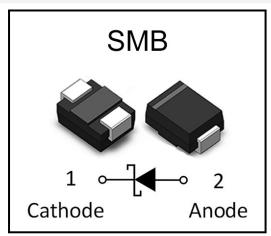


Fast Recovery Rectifier Diode

Features Package

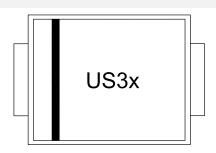
- · Low profile package
- · Ideal for automated placement
- · Glass passivated chip junction
- High forward surge capability
- · Super fast reverse recovery time
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260°C



Description

- Package: DO-214AA (SMB)
- Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant, halogen-free
- Terminals:Tin plated leads, solderable per J-STD-002 and JESD22-B102
- · Polarity: Cathode line denotes the cathode end

Making Code



Ordering information

	Part Number	US3A	US3B	US3D	US3F	US3G	US3J	US3K	US3M
	Marking	US3A	US3B	US3D	US3F	US3G	US3J	US3K	US3M
-	Base qty	3K							







Fast Recovery Rectifier Diode

Maximum Ratings and Electrical Characteristics@T_A=25°C unless otherwise noted

Symbol	Parameters	US	US	US	US	US	US	US	US	Units	
Syllibol	Farameters		3B	3D	3F	3G	3J	3K	3M	UiillS	
V_{RRM}	Maximum Recurrent Peak Reverse Voltage		100	200	300	400	600	800	1000	V	
V _{RMS}	Maximum RMS Voltage	35	70	140	210	280	420	560	700	V	
V_{DC}	Maximum DC Blocking Voltage	50	100	200	300	400	600	800	1000	V	
I _{AV}	Maximum Average Forward Rectified Current	3.0						Α			
	Forward Surge Current @60Hz	100					Α				
I _{FSM}	Half-sine wave,1 cycle, T _j =25°C										
IFSM	Forward Surge Current@1ms,	200									
	quare wave, 1 cycle, T _j =25°C										
V _F	Maximum Forward Voltage@I _{FM} =3.0A		1.0 1.3		1.7			V			
I_	Maximum DC reverse current@T _j =25°C		5						uA		
I _R	Maximum DC reverse current@T _j =125°C	100									
l ² t	I ² t Current squared time @1ms≤t≤8.3ms,T _j =25°C		41.5						A^2s		
t _{rr}	Maximum reverse recovery time @I _F =0.5A,		50 75		75		ns				
чr	I _R =1.0A,I _{rr} =0.25A	30		13				113			
C _j	Typical junction capacitance Measured at 1MHz and	60			40			24		pF	
	Applied Reverse Voltage of 4.0 V.D.C			40		24			Pi		
R _{θJA} ⁽¹⁾ Typical Thermal Resistance		65					°C/W				
T_J	T _J Operating JunctionTemperature Range		-55 to +150					°C			
T _{STG} Storage TemperatureRange		-55 to +150					°C				

Note: (1) Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.3° x 0.3° (8.0 mm x 8.0 mm) copper pad areas





Fast Recovery Rectifier Diode

Typical Performance Characteristics(T_J = 25 °C, unless otherwise noted)

Figure 1: I_{AV}-T_L Curve

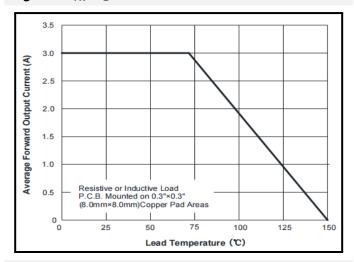


Figure 3:Typial Forward Voltage

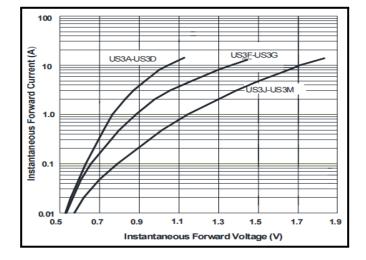


Figure 2:Surge Forward Current Capability

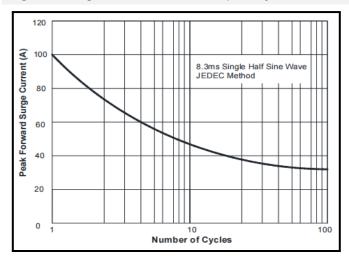
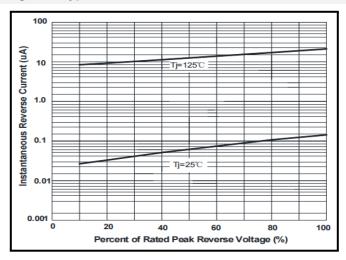


Figure 4:Typical Reverse Characteristics

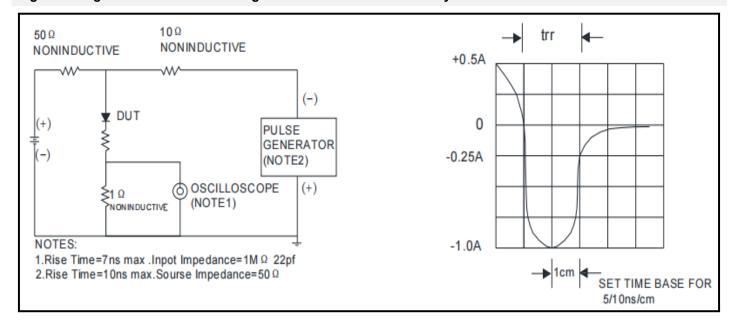




Fast Recovery Rectifier Diode

Typical Performance Characteristics(T_J = 25 °C, unless otherwise noted)

Figure 5:Diagram of circuit and Testing wave form of reverse recovery time

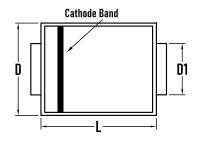


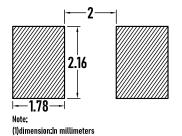




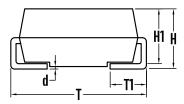
Fast Recovery Rectifier Diode

Outline Drawing - SMB

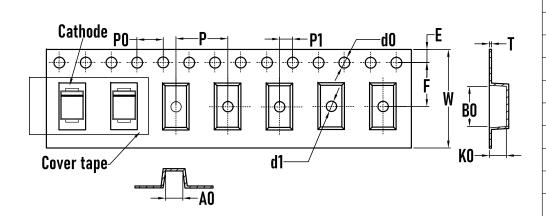




SYMBOL	MILLIMETER					
STIVIDUL	MIN	MAX				
D	3.40	3.80				
D1	1.70	2.30				
Т	5.10	5.70				
T1	0.80	1.40				
d	0.00	0.30				
H1	2.00	2.40				
Н	2.10	2.50				
L	4.30	4.70				

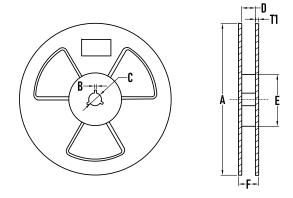


Packaging Tape - SMB



SYMBOL	MILLIMETER		
A0	3.60±0.1		
В0	5.45±0.1		
d0	1.50±0.1		
d1	1.50±0.1		
E	1.75±0.1		
F	5.50±0.1		
K0	2.30±0.1		
Р	8.00±0.1		
P0	4.00±0.1		
P1	2.00±0.1		
W	12.00±0.1		
Т	0.22±0.02		

Packaging Reel



SYMBOL	MILLIMETER			
Α	323±2			
В	3.0±0.2			
С	15.0±0.5			
D	13±2			
E	73±2			
T1	2.2±0.2			
Quantity	3000PCS			

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